

## COMPARISON SPECIFICATION

Change to the Paragraph beginning on Page 7, line 26:

Next, considering an exemplary one of the sites 40, and referring to FIGS. 2B and ~~2B2D~~, each one of the plurality of the dielectric members 22<sub>1</sub> is disposed over, and affixed to, a corresponding one of the sites 40 using epoxy 24, as shown. More particularly, the dielectric members 22<sub>1</sub> are affixed to the platform 20 and portions of the electrical leads 16. It is noted that the dielectric members 22<sub>1</sub> includes a recess, or ridge 23, having side walls 25. Such configuration is provided to increase the surface tension between the applied B-stage epoxy 24 and the dielectric member 22<sub>1</sub> thereby to prevent the liquid-like epoxy from dripping off of the dielectric member 22<sub>1</sub>.

## COMPARISON CLAIMS

12. (Amended) A method for packaging an-integrated circuit chips adapted to operate at microwave frequencies, comprising the steps of:

providing a lead frame having a plurality of sites therein, each site having electrical leads extending outwardly from an inner region of the site;

adhesively affixing each one of a plurality of plastic base sections over a corresponding one of the site;

connecting electrical wires between the integrated circuit chips to be packaged at each one of the plurality of

sites and the electrical leads at the corresponding one of the sites; and

adhesively affixing covers to encapsulate each one of the integrated circuits circuit chips and the electrical wires connected thereto within a cavity cavities formed by the corresponding one of the plurality of the affixed corresponding one of the covers and a corresponding one of the base sections.

14. (Amended) The A method recited in claim 12 for packaging an integrated circuit chip adapted to operate at microwave frequencies, comprising the steps of:

providing a lead frame having electrical leads extending outwardly from an interior region of the lead frame;

electrically connecting a conductive member of a base section to a bottom ground plane conductor of the integrated circuit chips with an-apertured dielectrics disposed between the sites of the lead frame and the conductive members and the with the apertures being in registration with the a corresponding one of the integrated circuit chips;

connecting electrical wires between the integrated circuit chip and the electrical leads;

and wherein the affixing comprises affixing the a plastic covers to provide a packages

-for the integrated circuit chips with such integrated circuit chips being disposed within a cavity cavities formed by the affixed cover and with a portion of the electrically conductive member being exposed exteriorly of the package.

15. A method for packaging an integrated circuit chip adapted to operate at microwave frequencies, comprising the steps of:

providing a lead frame having electrical leads extending outwardly from an inner region of the lead frame and a dielectric member of a base section, such dielectric member having an aperture;

connecting electrical wires between the integrated circuit chip and the electrical leads and a bottom ground plane conductor of the integrated circuit chip to an electrically conductive member of the base section with the integrated circuit chip being disposed in registration with the aperture;

adhesively affixing the base section and a cover to provide a package for the integrated circuit chip with such integrated circuit chip being disposed within a cavity formed by the base section and the cover and with a portion of the electrically conductive member being exposed exteriorly of the package.

Please add the following new claims

17. A method for package for an integrated circuit chip, comprising:  
providing an electrically conductive lead frame having electrical leads extending outwardly from an inner region;  
providing an adhesive material;  
providing a base section having a top surface;  
affixing a portion of the top surface to a bottom surface portion of the lead frame with the adhesive material, with portions of the electrical leads extending outwardly from the base section; and  
providing a plastic cover over the base section, the plastic cover having a bottom surface, a portion of the bottom surface affixed to a top surface portion of the lead frame

by the adhesive material, the base section and the cover being configured to provide a cavity when the cover and the base section are affixed with the integrated circuit chip being encapsulated within the provided cavity and

wherein during the affixing of the cover to the lead frame, the adhesive material extends into the cavity along a first direction and is confined within outer surface of sidewalls of such cover along an opposite direction by inner surfaces of said sidewalls of such cover and,

wherein the cover is provided with a recess disposed within sidewalls and wherein during the affixing, ends of the sidewalls are affixed to the base section with the recess being in each one of the ends of the sidewalls, and with such recess having bottom surface and a rear surface to hold the adhesive material allowing a portion of the adhesive material to extend beyond the bottom surface into the cavity along a first direction while the rear surface of such recess retains such adhesive material within the sidewalls of the cover as such material is urged along an opposite direction.

18. The method recited in claim 17 including providing the cover with a ridge disposed along ends of sidewalls of the cover; and including disposing the adhesive material in the ridge between the cover and the lead frame to affix the cover to the lead frame.